NC257-2 Paste Flux

Solder plus Support

Paste Flux

Features:

- Excellent Wetting - Wide Process Window -Tin-Lead and Lead-Free Compatible - Used for Ball Attach

Description:

NC257-2 Paste Flux is a no clean tacky/rework flux designed to wet virtually all solderable electronic surfaces, components, assemblies, and substrates. AIM NC257-2 Paste Flux may be used for general touch up or rework of printed circuit boards, and for attaching spheres to ball grid array (BGA) packages. The superior wetting ability of NC257-2 Paste Flux results in bright, smooth and shiny solder joints whether reflowed by hand, hot-air rework station, convection reflow oven, or vapor phase soldering systems. Residues that remain on surfaces after soldering are clear, leaving a cosmetically appealing repair that can be easily pin probed during in-circuit test. NC257-2 Paste Flux is compatible with all tin-lead and lead-free alloys and is suitable for a wide range of applications. NC257-2 Paste Flux can be brushed, dispensed, pin transferred, or stencil printed. NC257-2 Paste Flux is available in 10cc and 30cc syringes.

Flux Application:

When being used in rework, application should be limited to the area being worked. Application via dispense needle, brush or a cotton swab is recommended.

Cleaning:

- NC257-2 Paste Flux can be cleaned, if necessary, with saponified water or an appropriate solvent cleaner.
- Please refer to the AIM Cleaner Matrix for a list of suitable cleaning materials.

Handling and Storage:

- NC257-2 Paste Flux has a refrigerated shelf life of 1 year at 4°C (40°F) to 12°C (55°C), and 6 months at room temperature.
- Allow the solder paste to warm up completely and naturally to ambient temperature (2 hrs.) prior to use.
- Do not store new and used paste in the same container.

Safety:

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying Material Safety Data Sheet for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

Physical Properties:

Parameter	Value
J-STD-004B	REL1
Acid Number	150.02mg KOH per gram flux

Parameter	Value
Viscosity	Gel-like consistency
Residues	Clear, Colorless

Corrosion Testing:

Parameter	Requirements	Results
Copper Mirror (24 hrs @ 25°C, 50%RH)	IPC-TM-650-2.3.32	Low
Halide Test (Silver Chromate)	IPC-TM-650-2.2.33	Pass

Surface Insulation Resistance:

Reference	Property	Pass-Fail Criteria	Results
IPC-TM-650 method 2.6.3.3 85°C / 85% R.H.	Control coupons	>1E+9 Ω at 96 and 168 hrs	Pass
	Sample coupons – pattern up	>1E+8 Ω at 96 and 168 hrs	Pass
	Sample coupons – pattern down	>1E+8 Ω at 96 and 168 hrs	Pass
	Post-test visual inspection	No dendrite growth or corrosion	Pass